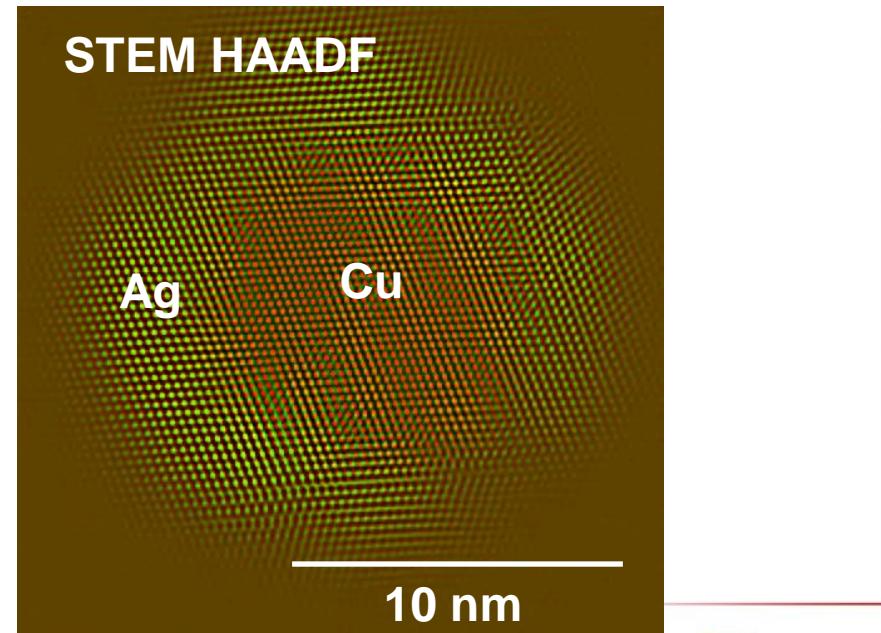
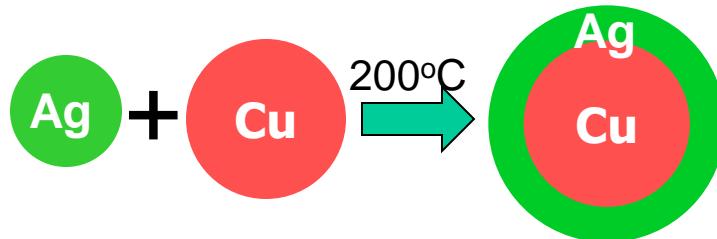


# In-situ TEM Heating Study of Cu and Ag Nanoparticle Interactions

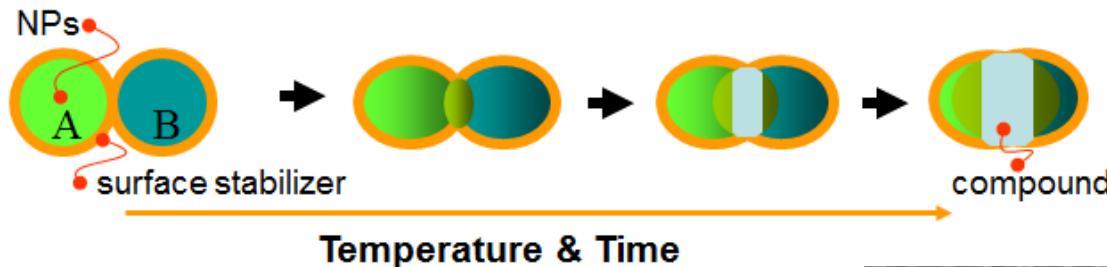
SAND2013-6236C

Ping Lu, Tim Boyle, Blythe Clark and Mike Chandross  
Sandia National Laboratories,  
Albuquerque, NM



# Motivations

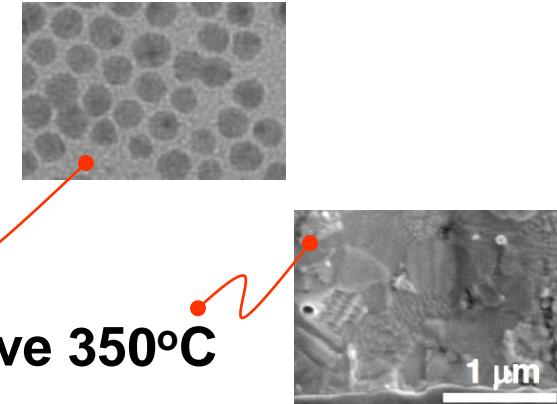
- Science – how do metallic nano-particles (NPs) interact at elevated temperatures? what are the equilibrium nano-alloy structures?



- Applications – metallic NP solders

- Low processing temperatures
- High service temperatures
- Ag/Cu system: bonding at  $\sim 200^{\circ}\text{C}$

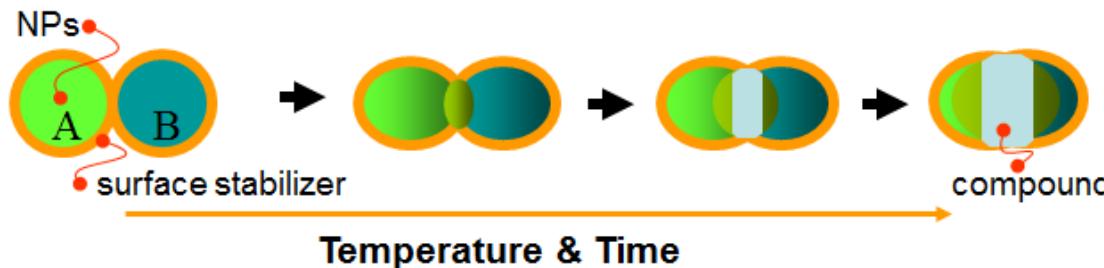
and applications at above  $350^{\circ}\text{C}$



- Few in-situ TEM experiments on dissimilar metal NPs

# R&D Goals & Approach

- In-situ TEM observation & Atomic-scale MD modeling

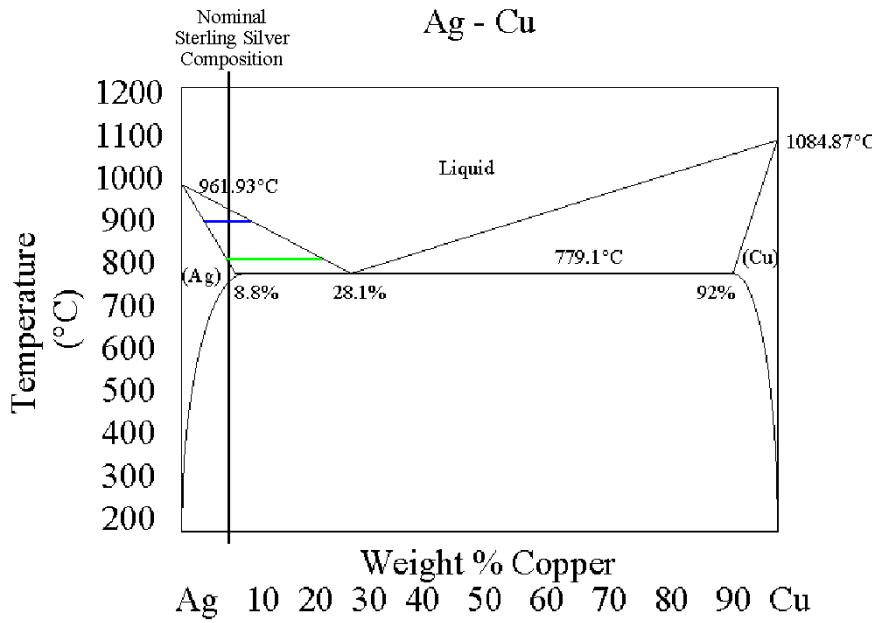


- In-situ, aberration-corrected STEM will be used to obtain *atomic-scale* images (at T, t).
- *Direct comparison* between the experiment and theory (MD) will be used to understand the reaction model.



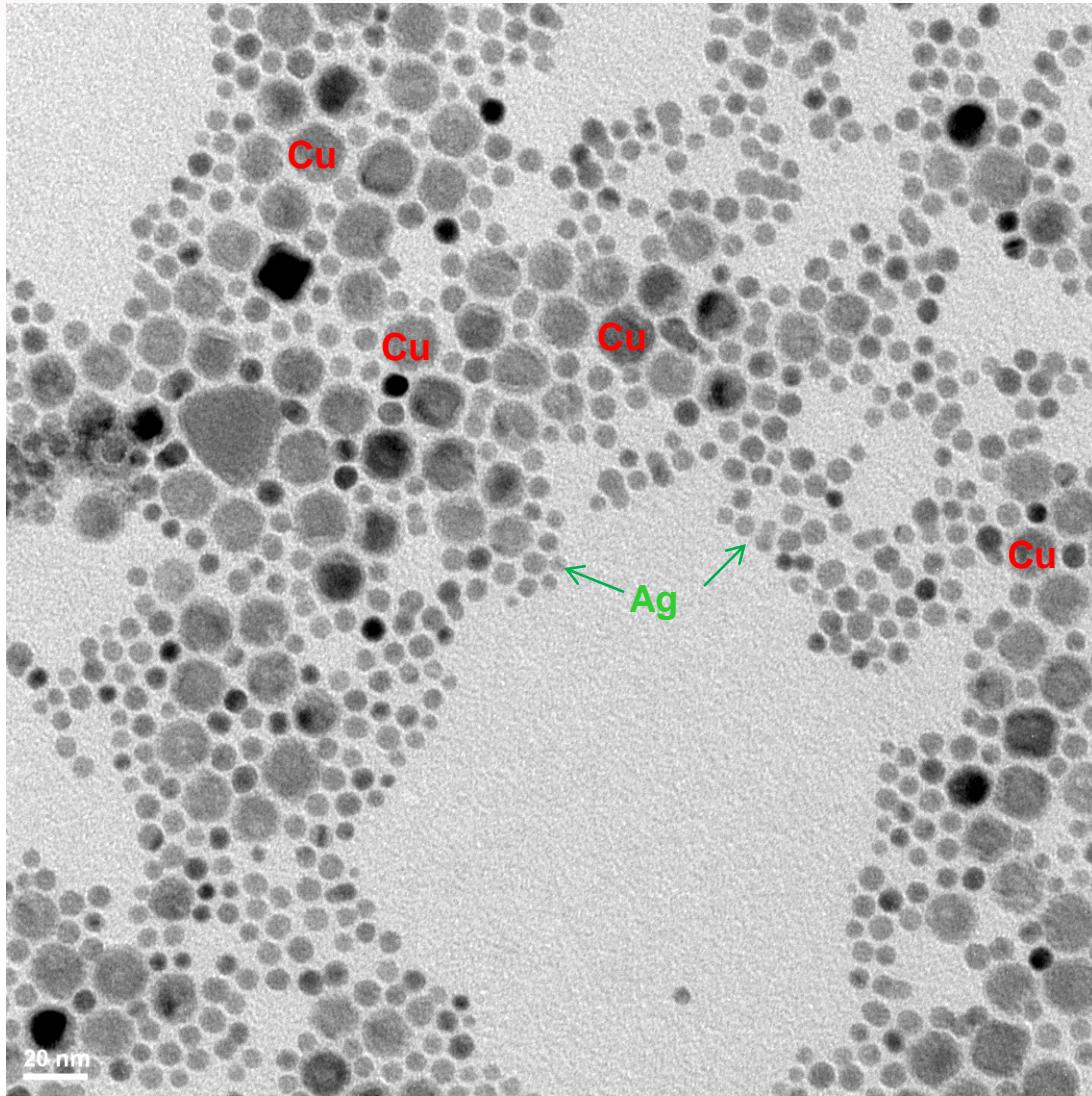
- FEI Titan G2 80-200kV – a probe corrector + *ChemiSTEM Technology*
- Protochips Aduro in-situ heating holder – 1000°C/sec heating rate
- Gatan 626 single tilt heating holder

# Ag/Cu Phase Diagram



- Eutectic system
- Not miscible
- This is bulk, is nanoscale different?

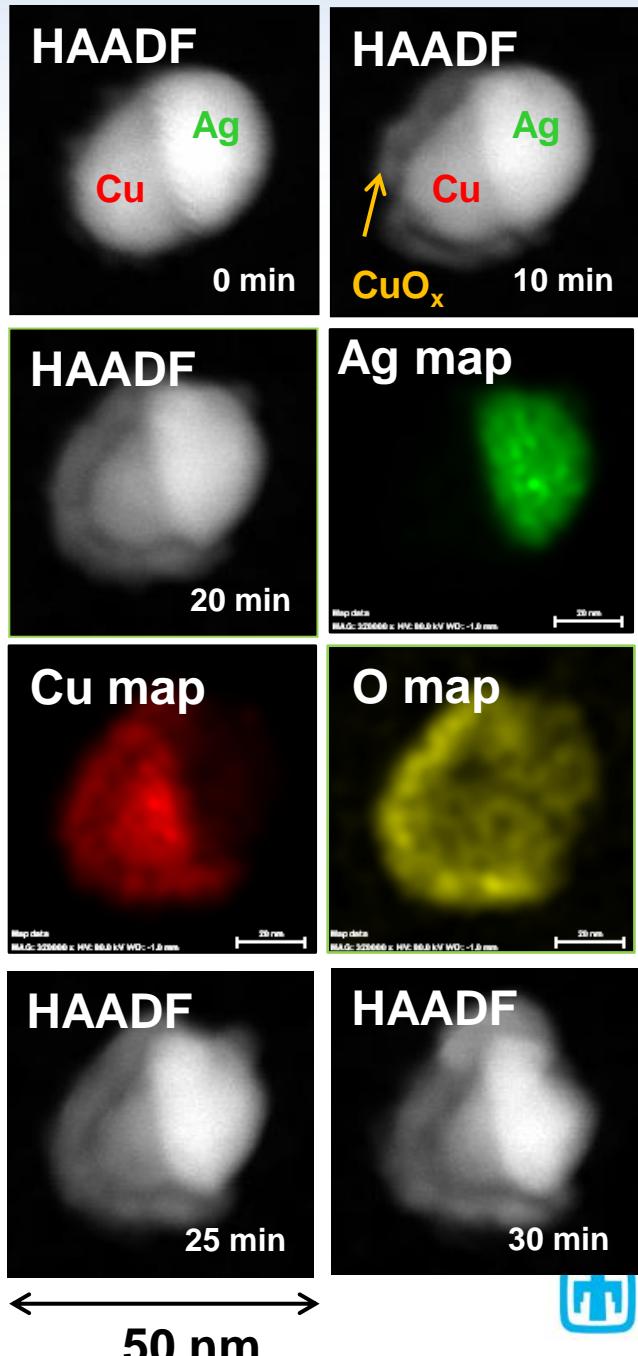
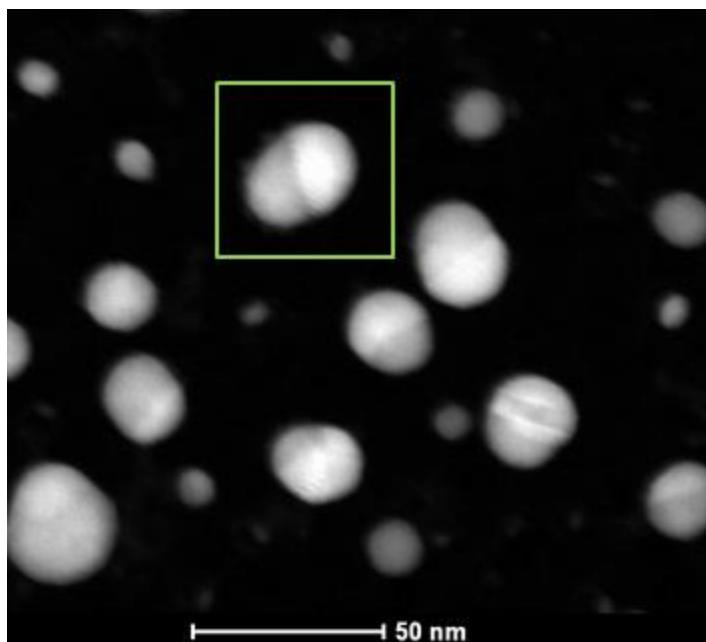
# Ag/Cu assembly before in-situ heating



- Cu NPs – 12-15nm
- Ag NPs – 6 nm
- Mixed in toluene and drop deposited on carbon film
- Ag NPs are present in between Cu NPs

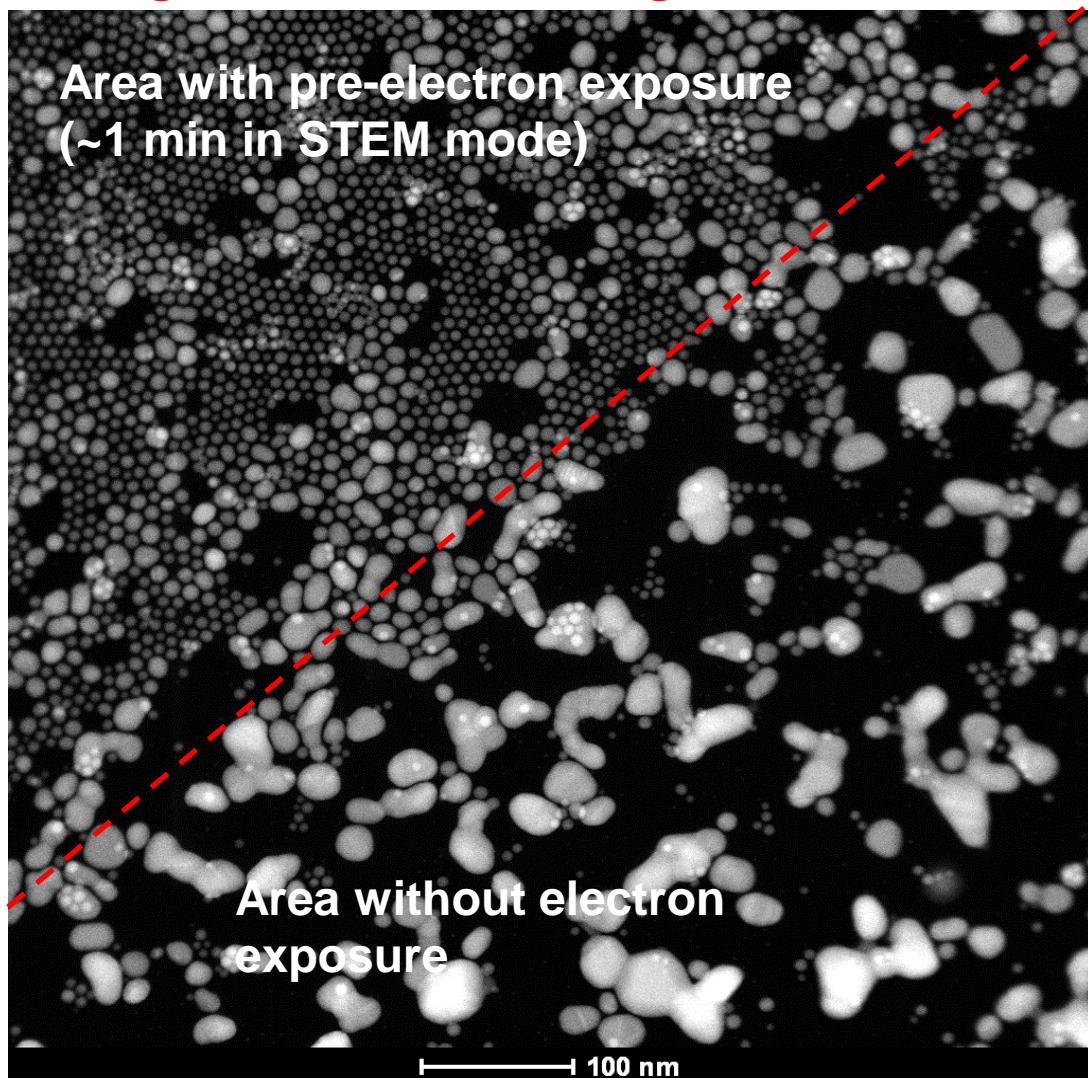
# In-situ TEM Challenges

- **Electron beam irradiation effects:**
  - Electron beam exposure makes metallic NPs less active.
  - Electron beam exposure also leads to oxidation of Cu NPs

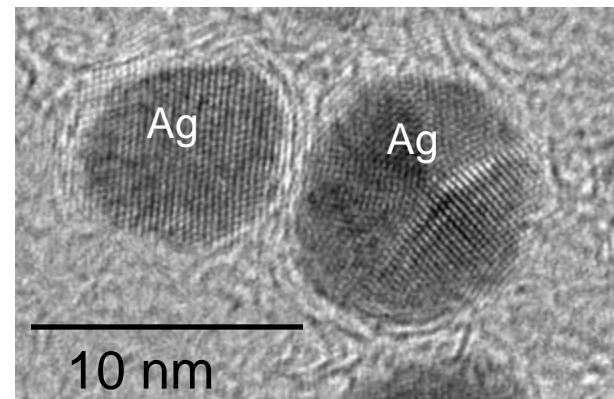


# Avoiding the electron irradiation effect is critical in in-situ experiment!

Ag NPs in-situ heating 160°C, 5 min

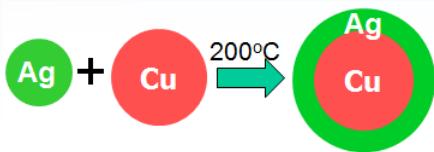


Formation of a graphitic shell on Ag NPs under electron beam irradiation

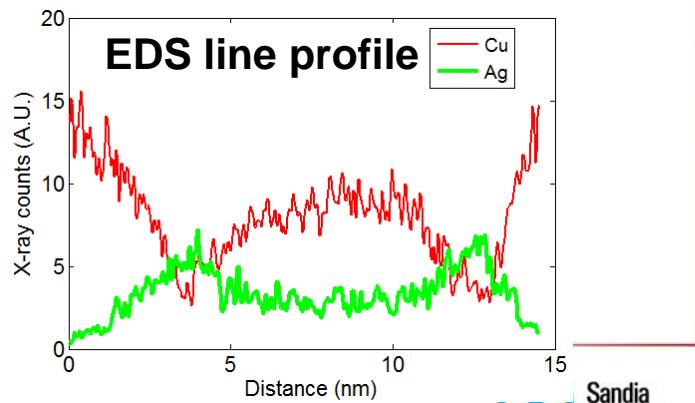
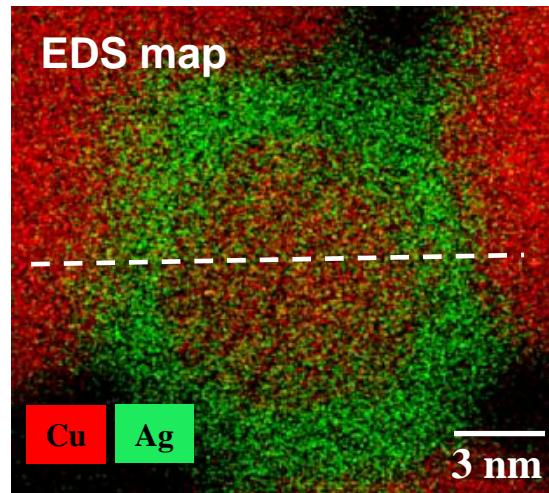
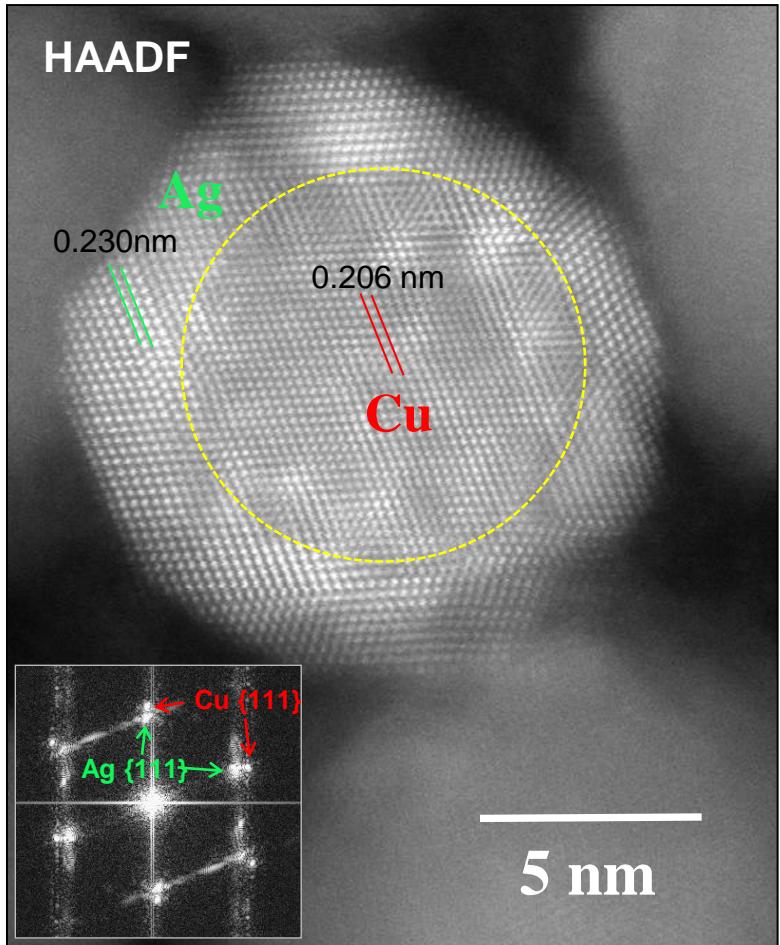


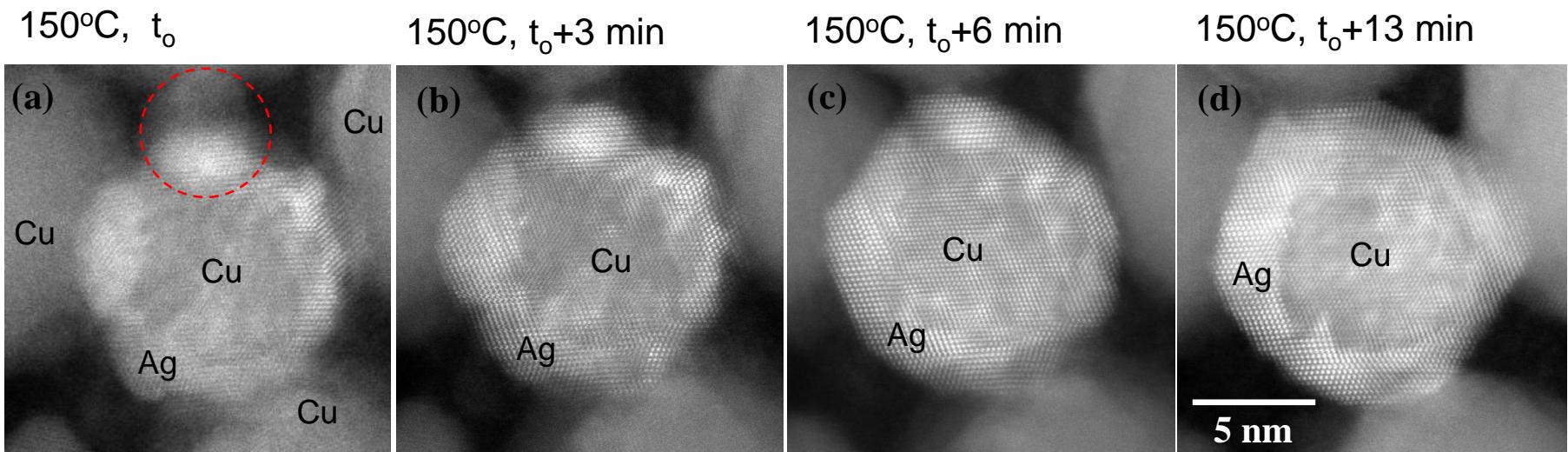
A similar effect was reported by Sutter *et al* for Au NPs at higher temperatures (Nano Letter 5, 2092, (2005))

# Cu/Ag NPs interact at temperatures as low as 150°C and form a Cu-core/Ag-shell structure



**Cube-on-cube orientation relationships between Cu-core and Ag-shell**

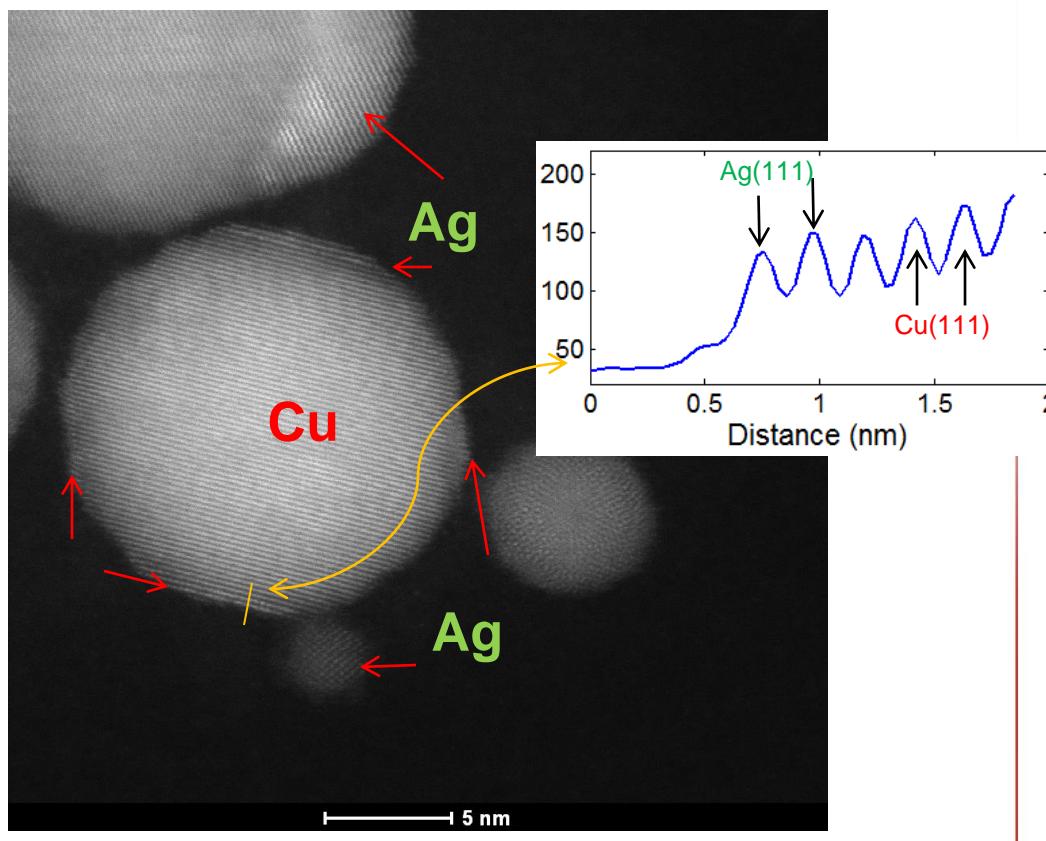
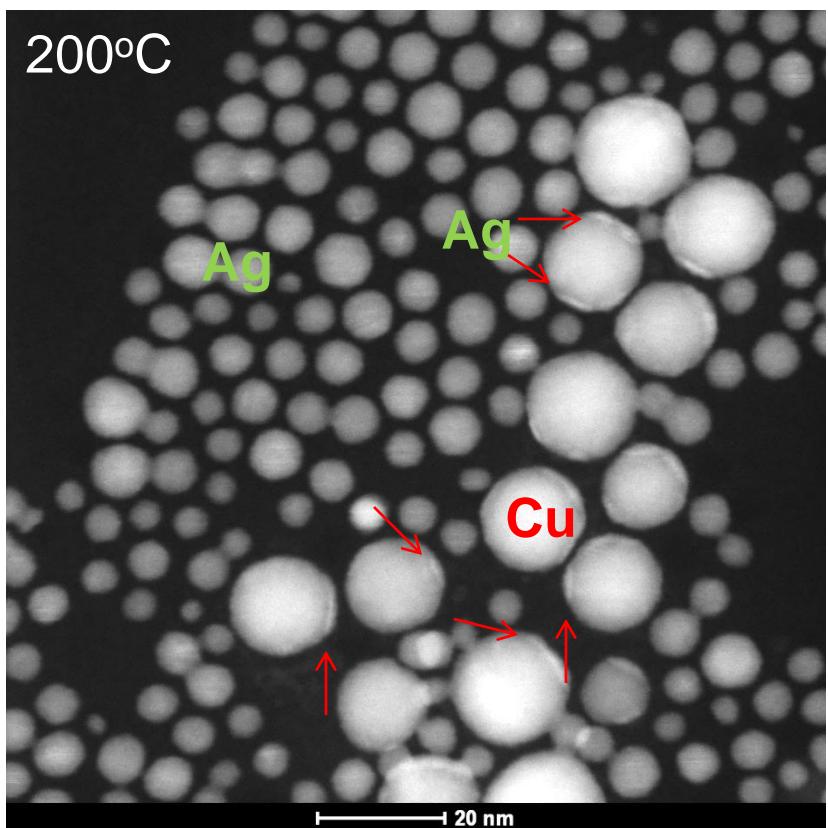




- Electron beam was off during the heating!
- The core/shell structure appears to be stable as long as no new interactions are initiated with neighboring NPs.

# Initial Ag/Cu Interaction

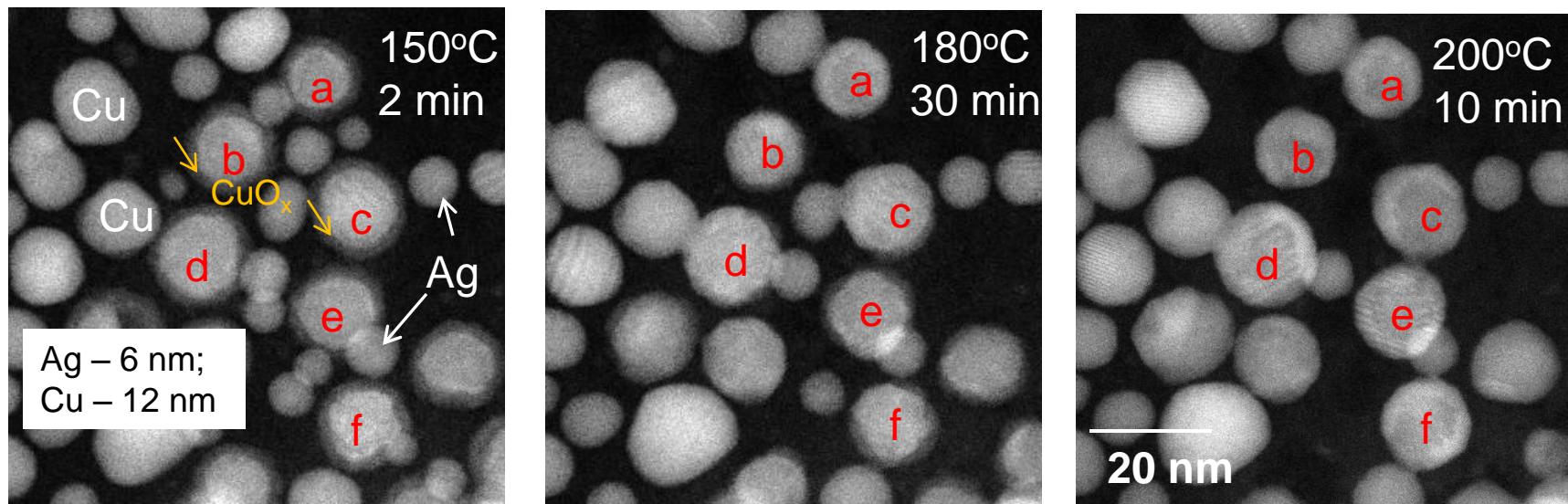
- Ag wetting on Cu {111} surface, and forming Ag{111}/Cu{111} type of epitaxial layer.
- Ag layers can be as thin as ~2-3 monolayer {111} Ag.



Small NPs are Ag (~6 nm)

# Effect of Cu oxide layer on Cu/Ag NP interaction

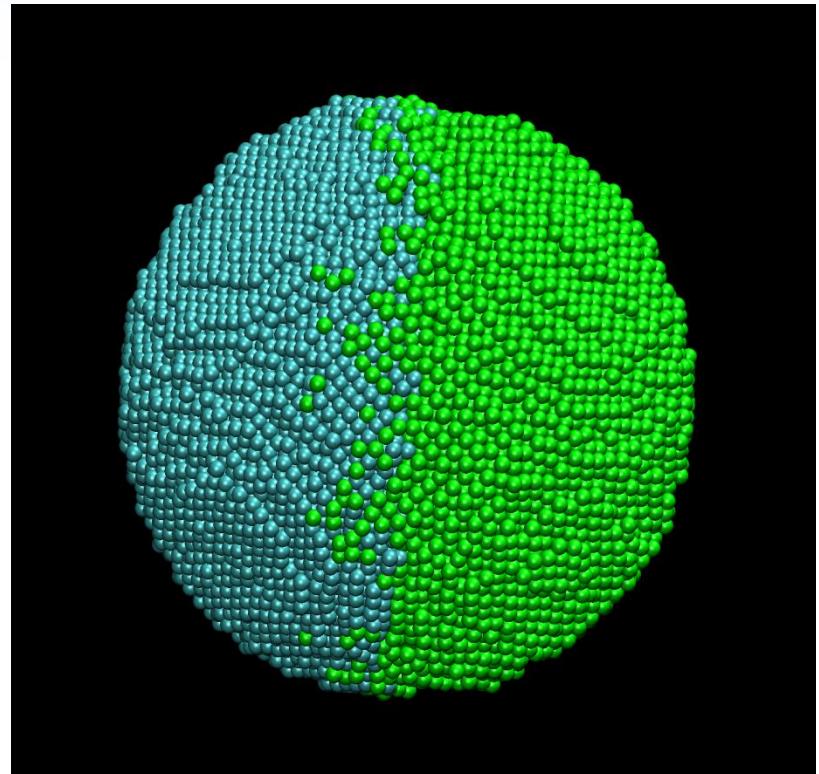
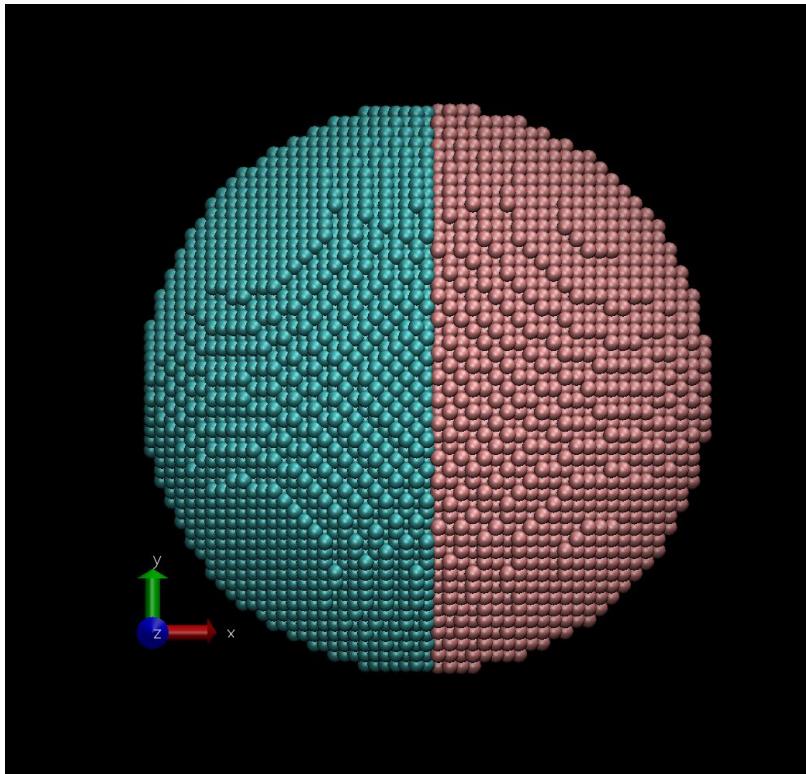
- The presence of Cu oxide layer on Cu NPs makes the Cu/Ag core-shell formation process longer



Cu NPs can be partially oxidized before the Cu/Ag interaction



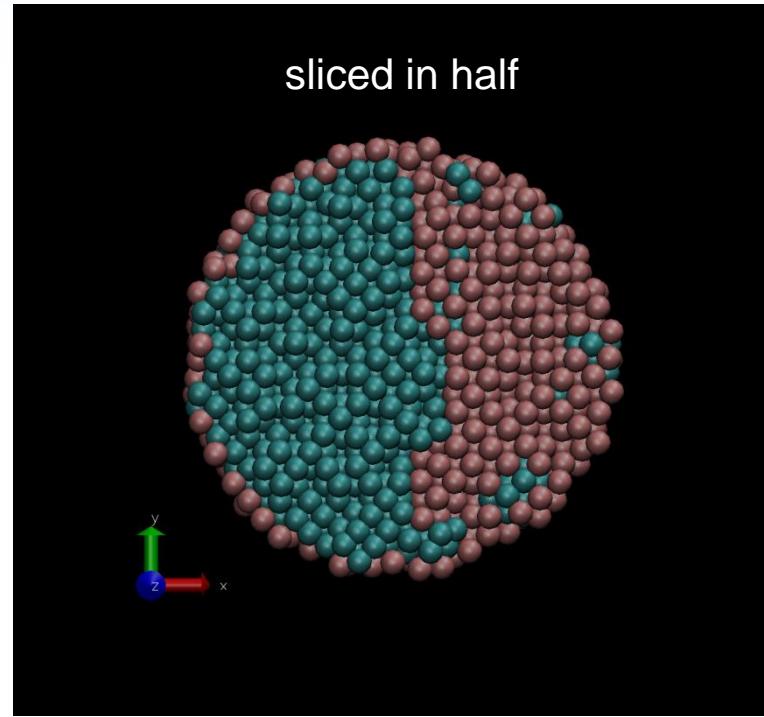
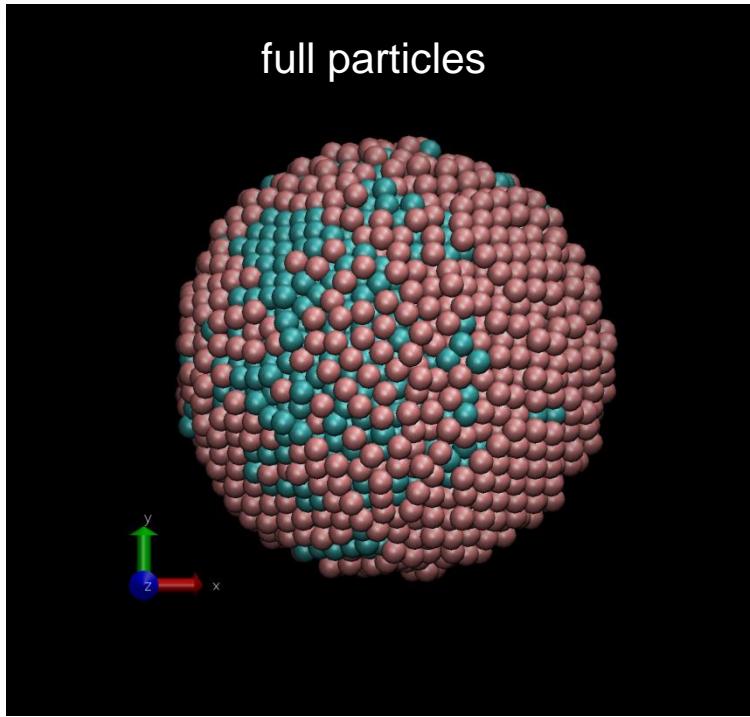
# Simulation Results



- 10nm Janus nanoparticles (left half Cu, right half Ag)
- At 800K (below eutectic) for < 1 ns



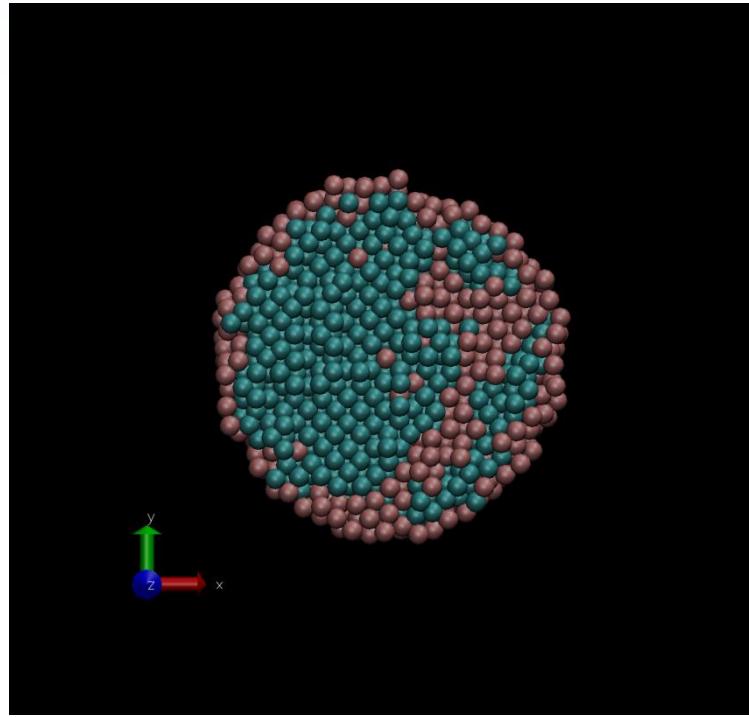
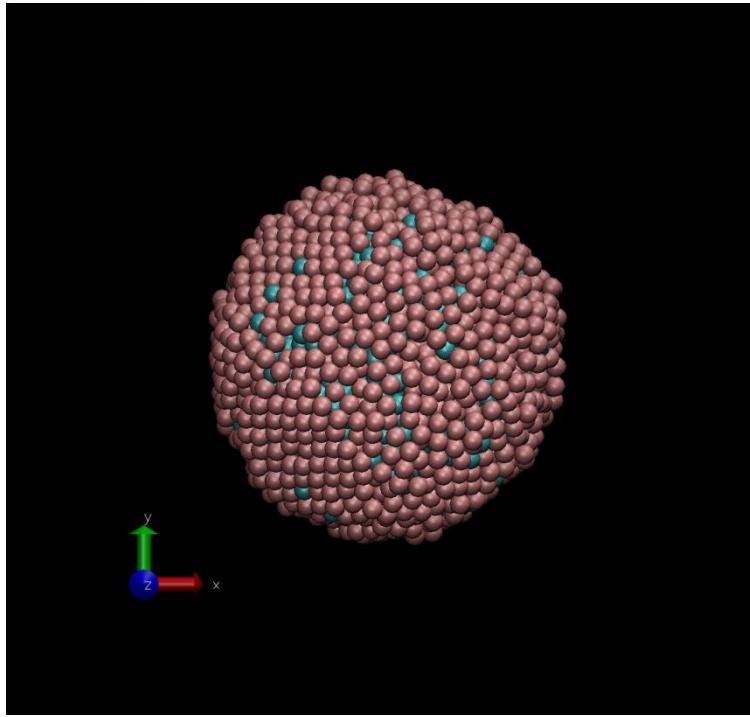
# Monte Carlo Simulations



- Simulation is not real time, but can be slow
- Randomly pick two particles to swap (with small translation)
- Accept move if energy is lower, or according to Boltzmann
- 5nm particle after 20M steps



# Longer Time Results



- 5nm, after 60M steps
- Shell is clearly favored at 800K

# Conclusion

- Ag (~6nm) and Cu (~12nm) NP interactions at elevated temperatures (150°-300°C) lead to formation a 3-D epitaxial Cu-core/Ag-shell structures.
- The interaction takes place initially by Ag wetting Cu along its {111} surfaces and forming an Ag {111}/Cu{111} epitaxial interface.
- The Cu-core/Ag-shell structure appears to be a thermally stable structure for the Cu-Ag nano alloys.
- The observation is possible only after avoiding the effect due to irradiation of electron beam.
- The new structure can be only explained as a nano-effect related to the large surface-to-volume ratio of the particles, and potentially could be exploited for several technological applications.

